

RoHS Compliance Material Declaration Report

Company: Pericom

Address: 3545 North First Street,
San Jose,
CA, 95134

Phone number: (408) 435 0800

Contact Pericom Customer Service for Additional Inquiries

Date: 7/26/2006

| Part Detail | | | | | |
|---------------------|--|-------------------------------|--------------|------------------------|------------------------------|
| Pericom Part Number | | Manufacturer part description | Package Type | Number of Pin/Terminal | Component overall weight (g) |
| PI74STX2G4245UE | | 2 Bit Level Shifting Buffer | MSOP | 8 | 0.022 |

| RoHS Compliance | | |
|--|----------------------------------|------------------------------------|
| Is Part compliant to EU RoHS Directive? [1] Yes, [2] Yes with tech exemption* [3] Yes but needs product application exemption* [4] No | RoHS tech exemption [2] details. | Date Component was RoHS Compliant. |
| Yes | N/A | Nov.5, 2004 |

| Content of RoHS restricted materials (g) | | | | | | |
|--|---------|---------|---------------------|--------------------------------|--------------------------------------|---|
| Lead | Cadmium | Mercury | Hexavalent Chromium | Polybrominated biphenyls (PBB) | Polybrominated Diphenylethers (PBDE) | RoHS restricted substance added intentionally? For what reason? |
| 0 | 0 | 0 | 0 | 0 | 0 | N/A |

| Component Soldering Process | | | | | | |
|---|-------------------------------|---|--|-------------------------------------|--------------------------|-----------------------------|
| Interconnect Composition, (Metallurgy of the lead/terminal) | JEDEC JEDS97 Pb-free Category | Compatible with a 260C 10s Pb-Free assembly process | Backward compatible with SnPb assembly | Maximum Processing Temperature (°C) | Max Temperature Duration | Max Number of reflow cycles |
| Sn | e3 | Yes | Yes | 260 | 40 | 3 |

| Plastics (if applicable) | | | |
|--------------------------|--|-----------------|--------------------------------|
| Oxygen Index | Type of plastic material used in the component | Fire: UL Rating | MSL Level (per JEDEC STD 020C) |
| >28% | Epoxy Resin | V-0 | 1 |

| Tin (Sn) Plating (If Applicable) | | | | | |
|---|----------------------------|---|--------------------------|---|------------------------------|
| Tin (Sn) Plating – is it Matte (M) or Bright (B)? | Tin (Sn) Plating Thickness | Tin (Sn) plating is there a Nickel (Ni) Barrier? - Yes / No | Nickel Barrier Thickness | If no Nickel barrier is the tin (Sn) termination finish heat treated? | Performed Tin Whisker Test ? |
| M | 7 to 20 um | No | N/A | Yes, 150C / 1 Hr | Yes |

| Bismuth (Bi) |
|--------------------------------------|
| Bismuth (Bi) Content (if applicable) |
| 0 |